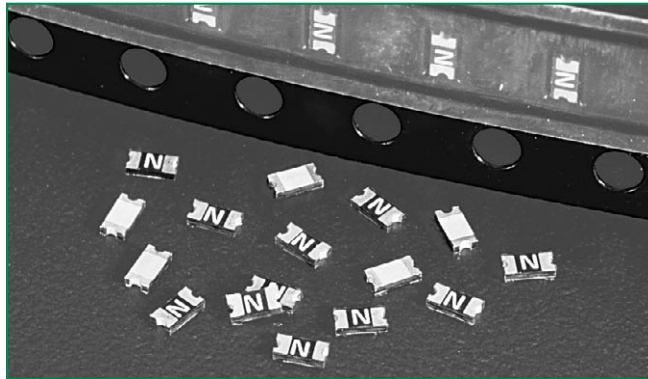




THE DATASHEET OF
043401.5NRP



434 Series Fuse



Description

The 434 series fast-acting surface mount fuse series is an ultra small (0603 size) thin-film device designed for secondary protection of circuits used in space constrained applications such as hand-held portable electronic devices.

For RoHS compliant and lead-free design, please refer to the Littelfuse 467 series thin film fuse.

Features

- The SlimLine 0603 fuse is an extremely small, low profile design (0603 chip size) utilizing thin-film technology to achieve precise control of electrical characteristics.
- The lower height profile produces a flat surface for improved performance in pick-and-place operations and an alternate solution for height critical applications.

Applications

Secondary protection for space constrained applications such as:

- Cell phones
- Battery packs
- Digital cameras
- DVD players
- Hard disk drives.

Agency Approvals

Agency	Agency File Number	Ampere Range
	E10480	250mA - 3A
	LR29862	250mA - 3A

Electrical Characteristics for Series

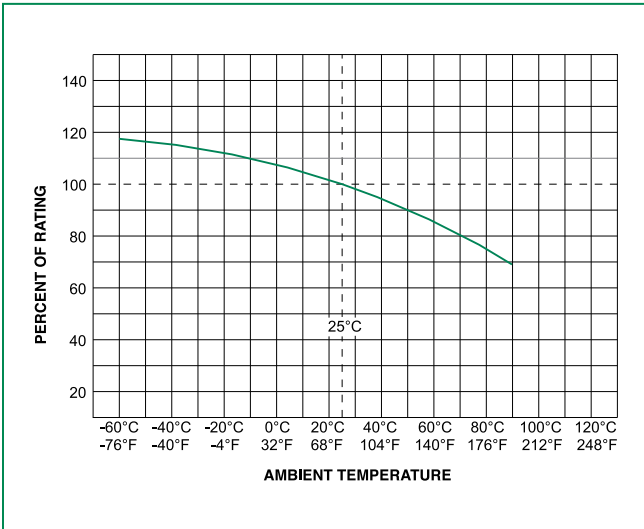
% of Ampere Rating	Opening Time at 25°C
100%	4 hours, Minimum
200%	5 seconds, Maximum.
300%	0.2 seconds, Maximum

Electrical Specifications by Item

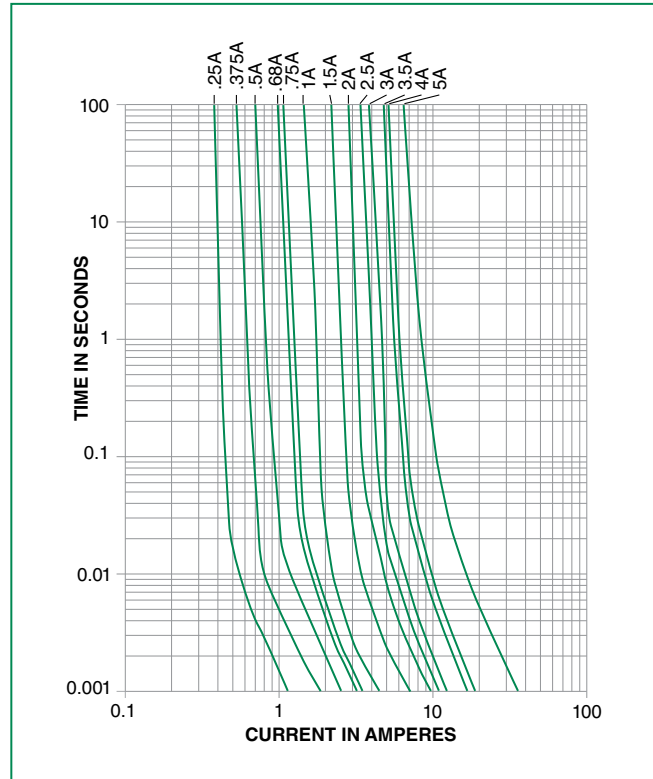
Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec)	Agency Approvals	
0.250	.250	32	50A @32 V AC/DC	0.3750	0.0030	x	x
0.375	.375	32		0.2650	0.0053	x	x
0.500	.500	32		0.1903	0.0087	x	x
0.680	.680	32		0.1250	0.0109	x	x
0.750	.750	32		0.1140	0.0171	x	x
1.00	001.	32		0.0720	0.0212	x	x
1.25	1.25	32	35A @32 V AC/DC	0.0540	0.0320	x	x
1.50	01.5	32		0.0480	0.0526	x	x
1.75	1.75	32		0.0390	0.0661	x	x
2.00	002.	32		0.0360	0.1040	x	x
2.50	02.5	32		0.0280	0.1750	x	x
3.00	003.	32		0.0230	0.1980	x	x
3.50	03.5	32		0.0190	0.2650	x	x
4.00	004.	32		0.0170	0.3520	x	x
5.00	005.	32		0.0130	1.2970	x	x

1. Measured at 10% of rated current, 25°C.
 2. Measured at rated voltage.

Temperature Derating Curve

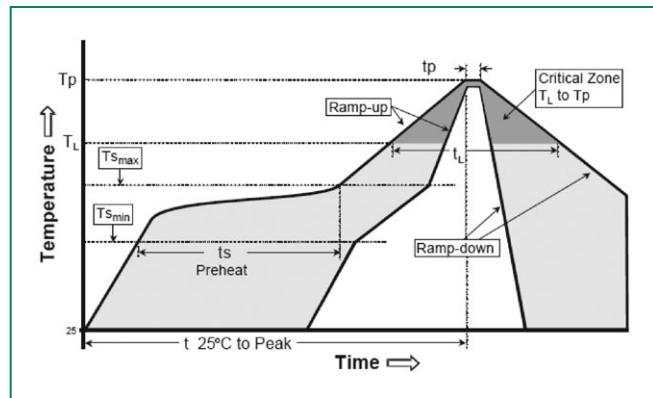


Average Time Current Curves



Soldering Parameters - Wave Soldering

Reflow Condition	Pb – Free assembly	
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)	5°C/second max	
$T_{s(max)}$ to T_L - Ramp-up Rate	5°C/second max	
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)	250 ^{+0/-5} °C	
Time within 5°C of actual peak Temperature (t_p)	20 – 40 seconds	
Ramp-down Rate	5°C/second max	
Time 25°C to peak Temperature (T_p)	8 minutes Max.	
Do not exceed	260°C	



Looking for pricing, stock, or lifecycle information?

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 [Littelfuse Inc. Information](#)

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